



## Material Content Data Sheet



<b>Sales Product Name</b>		TLD2326EL		<b>Issued</b>		16. September 2015		
<b>MA#</b>		MA001173204						
<b>Package</b>		PG-SSOP-14-5		<b>Weight*</b>		82.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.376	1.66	1.66	16627	16627
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8324	
wire	non noble metal	copper	7440-50-8	27.978	33.80	34.68	337990	346834
	non noble metal	copper	7440-50-8	0.080	0.10	0.10	972	972
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1217
	plastics	epoxy resin	-	4.634	5.60		55983	
	inorganic material	silicondioxide	60676-86-0	45.636	55.13	60.85	551313	608513
leadfinish	non noble metal	tin	7440-31-5	0.988	1.19	1.19	11940	11940
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9273	9273
glue	plastics	epoxy resin	-	0.121	0.15		1460	
	noble metal	silver	7440-22-4	0.363	0.44	0.59	4381	5841
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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